ASSP for Graphics Control

Graphics Display Controller

MB86290A

■ DESCRIPTION

The MB86290A is a graphics display controller for drawing and displaying graphics on a car navigation system or amusement unit.

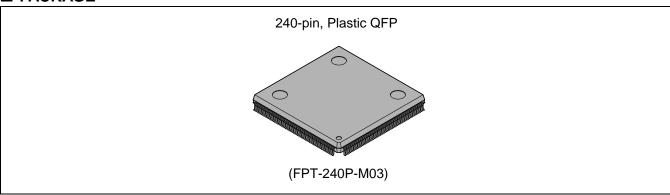
The MB86290A can process high-quality, true three-dimensional graphics at high speed using advanced features such as distortion control and hidden surface removal during expression of various levels of transparency and drawing in three-dimensional space. It can also process two-dimensional graphics with a smooth touch, for example, by drawing smooth lines and drawing polygons by connecting arbitrarily specified vertices.

■ FEATURES

- Operating frequency: 100 MHz (External clock of 14.32 MHz Max)
- Host interface: Enables direct connection to a CPU (Hitachi SH3/4 or NEC V832).
- Drawing features:
 - Drawing at a peak rate of 800 Mpixels per second (at an internal operating frequency of 100 MHz)
 - 2D drawing functions: Point, line, triangle, polygon, BLT, and pattern drawing
 - 3D drawing functions: Point, line, and triangle drawing, and hidden surface removal by Z-buffering
 - Special effects: Anti-aliasing, bold/dashed-line processing, alpha blending, Gouraud shading, texture mapping (bilinear filtering, perspective correct), and tiling

(Continued)

■ PACKAGE

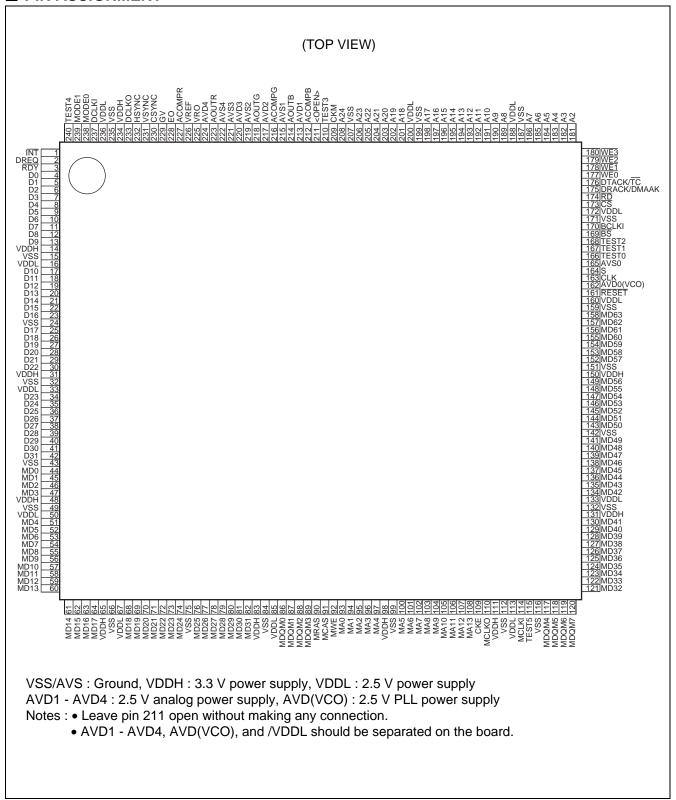




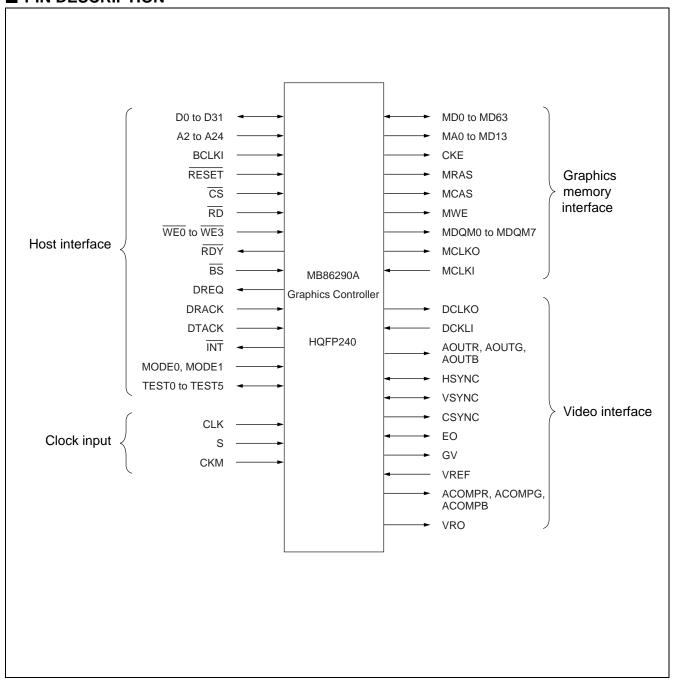
(Continued)

- Display features :
 - Maximum display resolution supported: 1024 x 768 pixels
 - Color display either with a color palette of 8 bits per pixel or directly using 5-bit RGB colors of 16 bits per pixel
 - · Overlaying four layers of screen, of which two lower layers can be divided into the left and right parts
 - Supporting two 64x64-pixel hardware cursors
 - Three-channel D/A converter integrated to output analog RGB signals
 - Capable of superimposing using an external synchronization mode
- Memory interface :
 - Using SDRAM as graphics memory at an operating clock speed of 100 MHz and data bus width of 64 bits. Capable of connecting up to 32 Mbytes (offering a throughput of 800 Mbps).
 - Power-supply voltage: Two power supplies at 2.5 V±0.2 V for internal circuits and 3.3 V±0.3 V for I/O parts
 - Package: Plastic QFP with 240 pins (with a lead pitch of 0.5 mm)
 - Power consumption: 1 W (at 100 MHz, $V_{DDL} = 2.5 \text{ V} \pm 0.2 \text{ V}$)
 - Process technology: 0.25 μm CMOS

■ PIN ASSIGNMENT



■ PIN DESCRIPTION



• Host Interface Pins

Pin Name	Input/output	Function
MODE0, MODE1	Input	Host CPU mode select
RESET	Input	Hardware reset
D0 to D31	Input/Output	Host CPU bus data
A2 to A24	Input	Host CPU bus address (Connect A24 to MWR in V832 mode.)
BCLKI	Input	Host CPU bus clock
BS	Input	Bus cycle start signal
<u>CS</u>	Input	Chip select signal
RD	Input	Read strobe signal
WE0	Input	D0 to D7 write strobe signal
WE1	Input	D8 to D15 write strobe signal
WE2	Input	D16 to D23 write strobe signal
WE3	Input	D24 to D31 write strobe signal
RDY	Output Tristate	Wait request signal ("0" for wait state with SH3; "1" for wait state with SH4 or V832)
DREQ	Output	DMA request signal (active low with both SH and V832)
DRACK/ DMAAK	Input	InputDMA request acknowledge signal (Connect this to DMAAK in V832 mode. Active high with both SH and V832.)
DTACK/TC	Input	DMA transfer strobe signal (Connect this to \overline{TC} in V832 mode. SH = active high, V832 = active low)
ĪNT	Output	Host CPU interrupt signal (SH = active low, V832 = active high)
TEST0 to TEST5	Input	Test signal

Note: The host interface can connect the MB86290A to the SH4 (SH7750) or SH3 (SH7709) manufactured by Hitachi Ltd. or to the V832 manufactured by NEC without any external circuit in between. (Using the SRAM interface allows the MB86290A to use another CPU.) The host CPU is set by the MODE pins as shown below.

MODE1 pin	MODE0 pin	CPU Type
L	L	SH3
L	Н	SH4
Н	L	V832
Н	Н	Reserved

- Notes: The host interface transfers data signals at a fixed width of 32 bits.
 - There are 23 lines for address signals handled in double words (32 bits) and 32 Mbytes of address
 - The external bus can be used at an operating frequency of 100 MHz Max.
 - The RDY signal at the low level sets the ready state in the SH4 or V832 mode; the signal at the low level sets the wait state in the SH3 mode. Note that the XRDY signal is a tristate output.
 - The host interface supports DMA transfer using an external DMA controller.

- The host interface generates a host processor interrupt signal.
 The RESET pin requires low level input of at least 300 μs after setting "S" (PLL reset signal) to high level.
- Fix the TEST signal at high level.
- In the V832 mode, connect the following pins as specified :

Pin Name	V832 Signal Name
A24	MWR
DTACK	TC
DRACK	DMAAK

Video Interface Pins

Pin Name	Input/output	Function
DCLKO	Output	Display dot clock signal output
DCLKI	Input	External synchronous dot clock signal input
AOUTR	Analog output	Analog video (R) signal output
AOUTG	Analog output	Analog video (G) signal output
AOUTB	Analog output	Analog video (B) signal output
HSYNC	Input/output*	Horizontal sync signal output Horizontal sync signal input in external synchronization mode
VSYNC	Input/output*	Vertical sync signal output Vertical sync signal input in external synchronization mode
CSYNC	Output	Composite sync signal output
EO	Input/output*	Even/odd-number field identification output Even/odd-number field identification input in external synchronization mode
GV	Output	Graphics/video select signal
VREF	Analog output	Reference voltage input pin
ACOMPR	Analog output	R-signal compensation pin
ACOMPG	Analog output	G-signal compensation pin
ACOMPB	Analog output	B-signal compensation pin
VRO	Analog output	Reference current setting pin

^{*:} Input voltage level: 5 V tolerant

Notes: • The video interface contains an 8-bit D/A converter to output analog RGB signals.

- Using an additional external circuit, the video interface can use CSYNC signals to generate composite video signals.
- The video interface can output analog RGB signals synchronized with external video signals. The mode for synchronization with the DCLKI signal can be selected as well as the mode for synchronization with a set dot clock as for normal display.
- The HSYNC and VSYNC signals must be pulled up outside the LSI as they enter the input state upon reset.
- Terminate the AOUTR, AOUTG, and AOUTB pins with a resistance of 75 Ω .
- Input 1.1 V to the VREF pin. Between this pin and analog ground, insert a bypass capacitor (one with a superior high-frequency characteristic such as a laminated ceramic capacitor).
- Connect the ACOMPR, ACOMPG, and ACOMPB pins to the 0.1μF ceramic capacitor ahead of the analog power supply.
- Connect the VRO pin to the analog ground with a 2.7 k Ω resistor.
- The input voltage levels of the HSYNC, VSYNC, and EO signals are 5 V tolerant. Do not input 5 V to these pins with the power supply off. (See ABSOLUTE MAXIMUM RATINGS.)
- For noninterlaced display in external synchronization mode, input "0" to the EO pin, for example, using a pull-down resistor.
- The GV signal serves to switch between graphics and video for chroma keying. The pin outputs a low level signal to select video.

• Graphics Memory Interface Pins

Pin Name	Input/output	Function
MD0 to MD63	Input/output	Graphics memory bus data
MA0 to MA13	Output	Graphics memory bus data
CKE	Output	Clock enable
MRAS	Output	Row address strobe
MCAS	Output	Column address strobe
MWE	Output	Write enable
MDQM0 to MDQM7	Output	Data mask
MCLKO	Output	Graphics memory clock output
MCLKI	Input	Graphics memory clock input

- Notes: The graphics memory interface connects the MB86290A to the external memory used for graphical image data. The interface can directly accept 64 Mbit SDRAM (with a 16-bit or 32-bit data bus) without any external circuit.
 - The data signal can be selected between 64 bits and 32 bits. To use the 32-bit signal, leave the MD32 to MD63 and MDQM4 to MDQM7 pins open.
 - Connect the MCLKI pin to the MCLKO pin.

Clock Input Pins

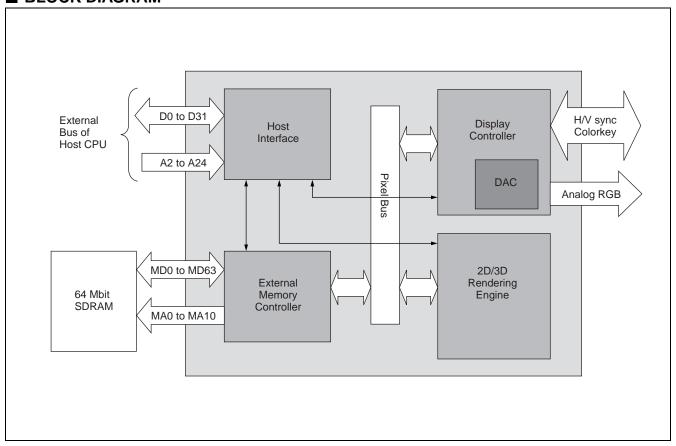
Pin Name	Input/output	Function
CLK	Input	Clock input signal
S	Input	PLL reset signal
CKM	Input	Clock mode signal

- Notes: The clock input block inputs the clock signal that serves as the basis for the reference clock for the internal operating clock and display dot clock. Usually input 4 Fsc (= 14.31818 MHz). The internal PLL generates the internal operating clock signal of 100.22726 MHz and the display reference clock signal of 200.45452 MHz.
 - The internal operating clock signal to be used can be selected between the clock signal (CLK input multiplied by 7) generated by the internal PLL and the bus clock BCLKI input to the host CPU interface. Select the BCLKI input to use the host CPU bus at 100 MHz.

СКМ	Clock Mode		
L	Select internal PLL output.		
Н	Select host CPU bus clock (BCLKI) .		

Note: Immediately after turning the power supply on, input a pulse whose low level <u>period</u> is 500 ns or more to the S pin before setting it to high level. After the S signal goes high, input the <u>RESET</u> signal at low level for 300 μs or more.

■ BLOCK DIAGRAM



■ FUNCTION BLOCKS

Host Interface

This block allows the MB86290A to be connected to the SH3 or SH4 microprocessor manufactured by Hitachi Ltd. without any external circuit in between. The block provides an interface to transfer display list and texture pattern data directly from main memory to the CREMSON graphics memory or internal register using the external DMA controller.

• External Memory Controller

This block controls the external synchronous DRAM connected as graphics memory. The 64-bit or 32-bit data bus is selected and the maximum operating frequency is 100 MHz.

• Display Controller

This block contains a three-channel D/A converter supporting XGA (1024x768 pixels) display and outputs analog RGB signals. The block enables superimposing using the external synchronization mode. It can divide the screen into the left and right parts to display different contents and to scroll them separately. It can also display animations smoothly using double buffering. In addition, it can overlay up to four screens, where the image color blending function can be used to display maps through the console screen as a transparency.

• 2D/3D Rendering Engine

This block draws images in two or three dimensions.

2D drawing

The block provides the anti-aliasing and alpha blending functions to display high-quality images even on a low-resolution LCD.

• 3D drawing

The block provides true 3D drawing functions such as perspective texture mapping and Gouraud shading.

■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Ra	Unit		
rarameter	Symbol	Min	Max	Oilit	
Dower aupply voltage	V _{DDL} *1	- 0.5	+ 3.0	V	
Power-supply voltage	V _{DDH}	- 0.5	+ 4.0	V	
Input voltage	Vı		VDDH + 0.5 (< 4.0)	V	
Input voltage	V _{IV} *2	- 0.5	VDDH + 4.0 (< 6.0)	V	
Output current	lo	– 13	+ 13	mA	
Power pin current	I POW	_	60	mA	
Ambient energting temperature	TA	0	70	°C	
Ambient operating temperature	I A	- 40* ³	+ 85*3		
Ambient storage temperature	Tstg	– 55	+ 125	°C	

^{*1 :} The analog and PLL power supplies are included.

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

^{*2 :} The HSYNC, VSYNC, and EO signals are input.

^{*3 :} Model supporting a wider range of temperatures

■ RECOMMENDED OPERATING CONDITIONS

Dorometer	Symbol		Value		Unit
Parameter	Symbol	Min	Тур	Max	Unit
	V _{DDL} *1	2.3	0.5		
Power supply voltage	V _{DDL} *2	2.6*6	2.5	2.7	V
Power-supply voltage	V _{DDH}	3.0	3.3	2.6	V
	V DDH	3.5*6	3.3	3.6	
Input voltage (High Iovel)	ViH	2.0	_	VDDH + 0.3	V
Input voltage (High level)	V _{IHV} *3	2.0	_	5.5	V
Input voltage (Levy level)	VıL	- 0.3	_	+ 0.8	V
Input voltage (Low level)	V _{ILV} *3	- 0.3	_	+ 0.8	V
VREF pin input voltage	Vref	1.05	1.10	1.15	V
VRO pin external resistor	Rvro	_	2.7	_	kΩ
AOUT pin external resistor*4	RAOUT	_	75	_	Ω
ACOMP pin external capacitor*5	Сасомр	_	0.1	_	μF
Ambient energting temperature	т.	40		+ 85	°C
Ambient operating temperature	TA	- 4 0	_	+ 70*6	

^{*1 :} The analog and PLL power supplies are included.

Notes: • The VDDL and VDDH power supplies can be turned on or off in either order.

Note, however, that the VDDH voltage must not be applied alone continuously for several seconds.

- Do not input the HSYNC, VSYNC or signal with the power-supply voltage not applied. (See "Input voltage" in "■ ABSOLUTE MAXIMUM RATINGS".)
- After turning the power on, input a pulse remaining at low level for at least 500 ns to the S pin. Then, set the S pin to high level and input the RESET signal held at low level for at least 300 μs.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

^{*2 :} The HSYNC, VSYNC, and EO signals are input.

^{*3:} AOUTR, AOUTG, and AOUTB pins

^{*4 :} AOUTR, AOUTG, AOUTB pins

^{*5 :} ACOMPR, ACOMPG, ACOMPB pins

^{*6:} Using BCLKI at 90 MHz or more

■ ELECTRICAL CHARACTERISTICS

1. DC Characteristics

 $(V_{DDL} = 2.5 \text{ V} \pm 0.2 \text{ V}, V_{DDH} = 3.3 \text{ V} \pm 0.3, V_{SS} = 0.0 \text{ V}, T_{A} = 0 ^{\circ}\text{C to } +70 ^{\circ}\text{C})$

Parameter		Symbol		Value		
		Symbol	Min	Тур	Max	Unit
Output voltage (High	level) *1	Vон	V _{DDH} - 0.2	_	V _{DDH}	V
Output voltage (Low	level) *2	Vol	0.0	_	0.2	V
		IOH1*3	- 2.0	_	_	
Output current (High	Output current (High level)		- 4.0	_	_	mA
			- 8.0	_	_	7
			2.0	_	_	
Output current (Low	level)	l 0L2*4	4.0	_	_	mA
		lo _{L3} *5	8.0	_	_	
AOUT voltage*6	Full scale	- Ідоит	9.90	10.42	10.94	mA
AOO1 Vollage *	Zero scale	IAOUT	0	2	20	μΑ
AOUT voltage*7		Vaout	- 0.1	_	+ 1.1	V
Input leakage current		lι		_	± 5	μΑ
Pin capacitance		С	_	_	16	pF

^{*1 :} Value when $-100 \,\mu\text{A}$ current flows into output pins.

^{*2 :} Value when 100 μA current flows into output pins.

^{*3 :} Output characteristics of the MD0 to MD63, MDQM0 to MDQM7 pins

^{*4:} Output characteristics of the signals (excluding analog signals) other than those in *3 and *5

^{*5 :} MCLKO pin output characteristics

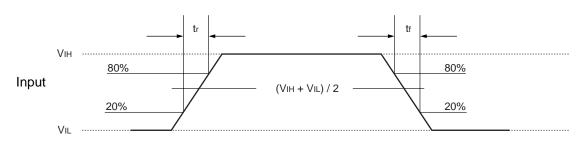
^{*6 :} AOUTR, AOUTG, and AOUTB pin output current. Conditions $V_{REF} = 1.10 \text{ V}$, $R_{VRO} = 2.7 \text{ k}\Omega$ (The full-scale output current calculation expression is $(V_{REF}/R_{VRO}) \times 25.575$)

^{*7:} AOUTR, AOUTG and AOUTB pins

2. AC Characteristics

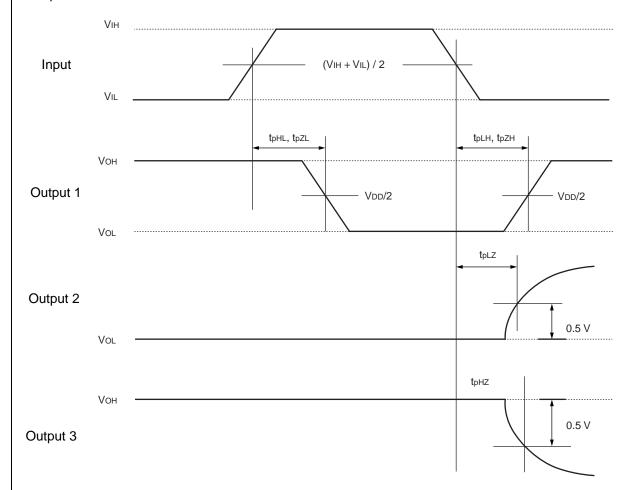
 $(V_{IH} = 2.0 \text{ V}, V_{IL} = 0.8 \text{ V})$

• Input measurement conditions



- t_r , $t_f \le 5 \text{ ns}$
- Input measurement standard : (VIH + VIL) / 2

• Output measurement conditions



• Output measurement standard : tpLz : VoL + 0.5 V

 t_{pHZ} : $V_{\text{OH}} - 0.5 \text{ V}$ Else : $V_{\text{DD}}/2$

(1) Host Interface

• Clock

Parameter	Symbol Condition		Val	Unit		
Farameter	Symbol	Condition	Min	Max	Onit	
BCLKI frequency	fвські	_	_	100	MHz	
BCLKI H period	t нвські	_	3.5	_	ns	
BCLKI L period	t lbclki	_	3.5		ns	

• Host interface signals

(Recommended operating conditions A, External load of 20 pF)

Paramatar.	Cumb al	Condition	Va	Unit	
Parameter	Symbol	Condition	Min	Max	Unit
Address setup time	t ADS		3.0	_	ns
Address hold time	t adh	_	1.0	_	ns
DC cotup time	t		3.5		no
BS setup time	t _{BSS}	_	3.0*3	_	ns
BS hold time	t BSH	_	0.0	_	ns
CS setup time	tono		3.5		no
C5 setup time	tcss	_	3.0*3	_	ns
CS hold time	t csH	_	0.0	_	ns
RD setup time	trds	_	3.0	_	ns
RD hold time	t RDH		1.0	_	ns
WE setup time	twes	_	3.0	_	ns
WE hold time	tweh	_	1.0	_	ns
Write data actus time	4	_	5.0	_	no
Write data setup time	twos		4.0*3		ns
Write data hold time	t wdh		1.0	_	ns
DTACK setup time	t daks	_	3.0		ns
DTACK hold time	t dakh	_	1.0	_	ns
DRACK setup time	t drks	_	3.0	_	ns
DRACK hold time	t drkh	_	1.0		ns
Bood data dalay time (to BD)	4		4.0	8.5	ns
Read data delay time (to \overline{RD})	t RDDZ	_	_	7.5*3	ns
Dood data dalay tima	4	*1	4.0	9.5	ns
Read data delay time	t _{RDD}	^1	_	6.0*3	ns
DDV dalou time (to CC) CU	_		3.0	9.0	ns
RDY delay time (to CS) SH	t RDYDZ		_	7.5*3	ns

(Continued)

(Continued)

Parameter	Cumbal	Condition	Va	Unit		
Parameter	Symbol	Condition	Min	Max	Oilit	
RDY delay time (to CS) V832	t RDYDZ	_	3.0	13.0	ns	
				10.5*³	ns	
RDY delay time	t RDYD	_	3.5	8.5	ns	
				7.0*3	ns	
DREQ delay time	t drqd		3.5	7.5	ns	
				6.5*3	ns	
MODE hold time	tмодн	*2		20.0	ns	

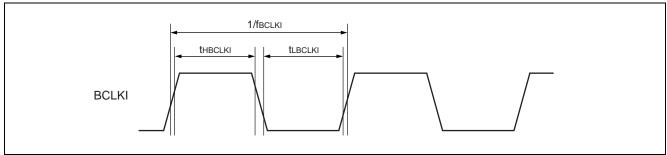
^{*1 :} Read data is output one cycle before the CPU samples it.

Note: The INT signal is output in synchronization with the internal operating clock. As a host interface signal, it is an asynchronous signal.

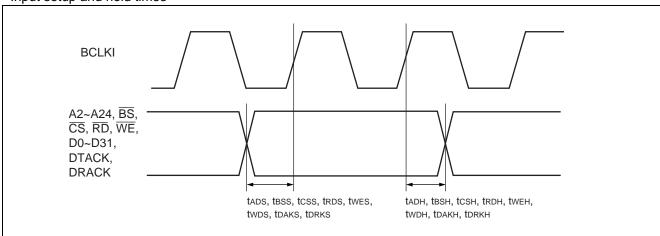
^{*2 :} Hold time for reset cancellation

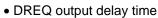
^{*3:} Using BCLKI at 90 MHz or more

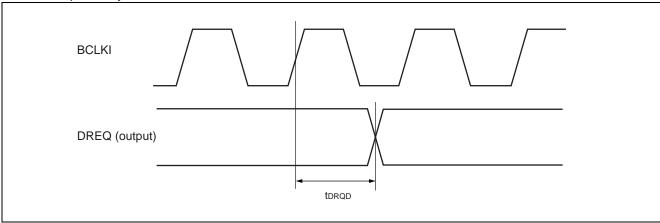


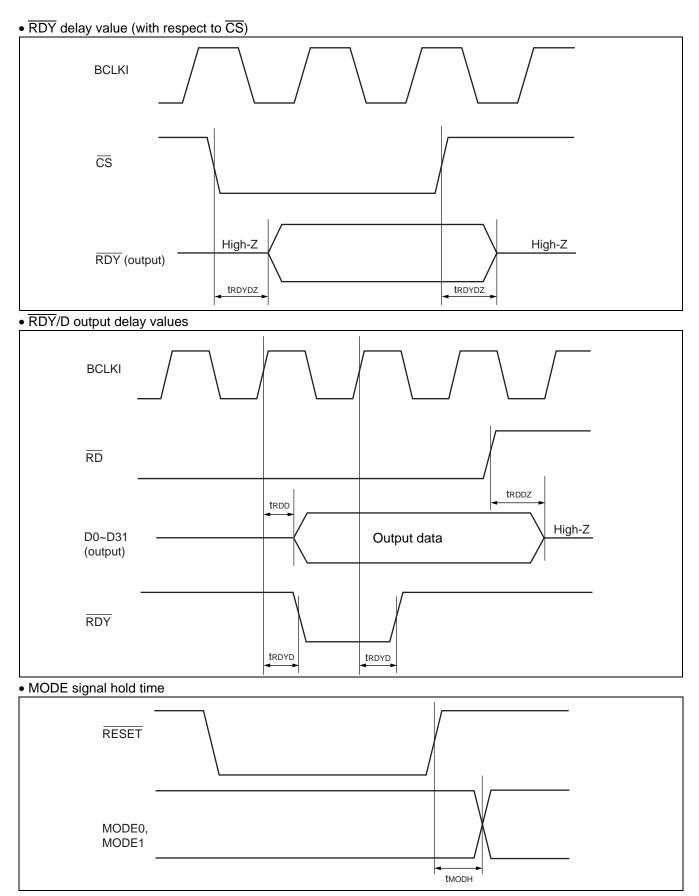


• Input setup and hold times









(2) Video Interface

Clock

Parameter	Symbol	Condition	Value			Unit
			Min	Тур	Max	Onit
CLK frequency	fськ	_		14.32	_	MHz
CLK H period	t HCLK	_	25		_	ns
CLK L period	t LCLK	_	25	_	_	ns
DCLKI frequency	fdclki	_	_	_	67	MHz
DCLKI H period	t HDCLKI	_	5	_	_	ns
DCLKI L period	t ldclki	_	5	_	_	ns
DCLKO frequency	fdclko	_	_	_	67	MHz

• Input signals

Parameter	Symbol	Condition	Value			Unit
	Symbol		Min	Тур	Max	Unit
HSYNC input pulse width	twnsynco	*1	3	_	_	clock
	twnsync1	*2	3	_	_	clock
HSYNC input setup time	tshsync	*2	10	_	_	ns
HSYNC input hold time	thhsync	*2	10	_	_	ns
VSYNC input pulse width	twnsync1	_	1	_	_	HSYNC 1 cycle
EO input setup time	tseo	*3	10	_	_	ns
EO input hold time	t HEO	*3	10	_	_	ns

^{*1 :} Applied only in PLL synchronization mode (CKS = 0) . The reference clock is the internal PLL's output with Cycle = 1/(14 fcLK).

• Output signals

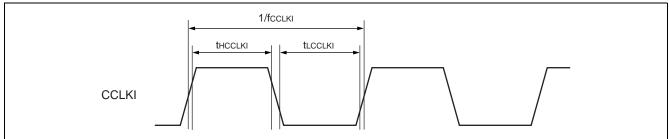
Parameter	Symbol	Condition	Value			Unit
raiailletei	Symbol		Min	Тур	Max	Offic
EO output delay time	t deo	*	_	_	10	ns
HSYNC output delay time	tohsync	_		_	10	ns
VSYNC output delay time	tovsync	_		_	10	ns
CSYNC output delay time	tdcsync	_		_	10	ns
GV output delay time	t DGV		_	_	10	ns

^{*:} The EO output varies at the same time as VSYNC is asserted.

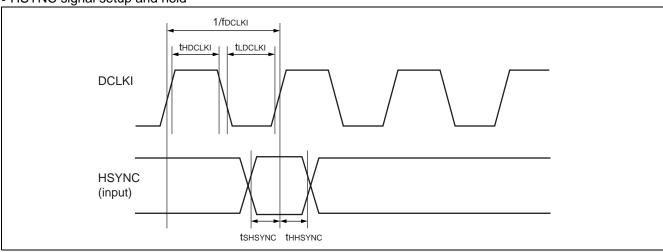
 $^{^*2}$: Applied only in DCLKI synchronization mode (CKS = 1) . The reference clock is DCLKI.

^{*3 :} Based on the edge with VSYNC negated.

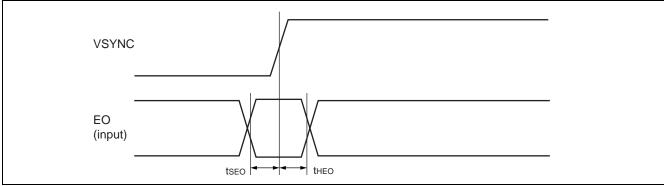




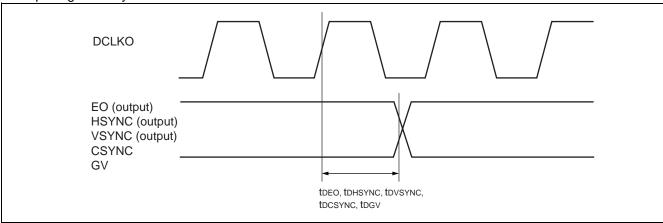
• HSYNC signal setup and hold



• EO signal setup and hold



Output signal delay



(3) Graphics Memory Interface • Clock

Parameter	Symbol	Condition	Value			Unit
			Min	Тур	Max	Oilit
MCLKO frequency	fмсько	_	_	_	100	MHz
MCLKO H period	tнмсько	_	1	_	_	ns
MCLKO L period	t LMCLKO	_	1	_	_	ns
MCLKI frequency	f MCLKI	_		_	100	MHz
MCLKI H period	t HMCLKI	_	1	_	_	ns
MCLKI L period	t lmclki	_	1	_	_	ns
MCLKI delay to MCLKO	toid	_	1	_	4	ns

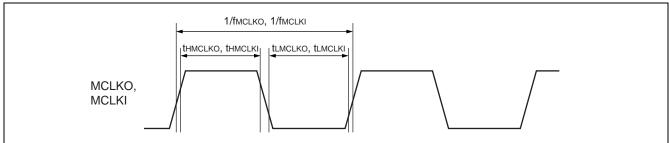
• I/O signals

Parameter	Cumbal	Condition	Value			l lm:4
	Symbol	Condition	Min	Тур	Max	Unit
MA, MRAS, MCAS, MWE, CKE Setup time	t MADS	*1	3.5	_	_	ns
MA, MRAS, MCAS, MWE, CKE Hold time	t madh	*1	1	_	_	ns
MDQM data setup time	t MDQMDS	*1	3.5	_	_	ns
MDQM data hold time	tмdqмdн	*1	1	_	_	ns
MD output data setup time	tmdods	*1	3.5	_		ns
MD output data hold time	tмдодн	*1	1			ns
MD input data setup time	tmdids	*2	3	_	_	ns
MD input data hold time	t MDIDH	*2	1	_	_	ns

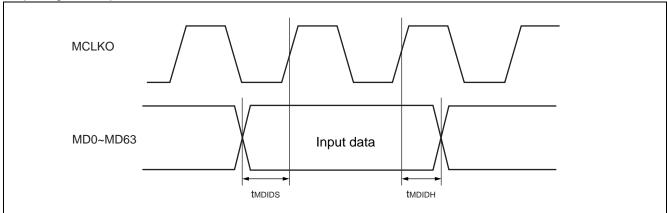
^{*1 :} Setup/hold time with respect to MCLKO.

^{*2 :} Setup/hold time with respect to MCLKI.

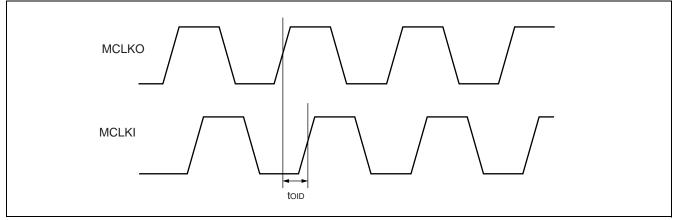




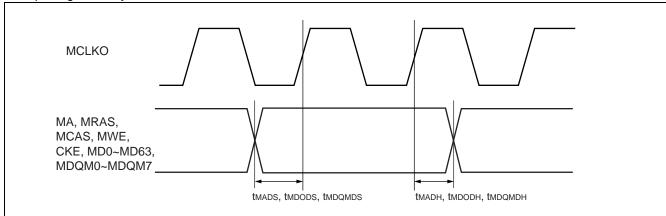
• Input signal setup and hold times



• MCLKI signal delay



Output signal delay



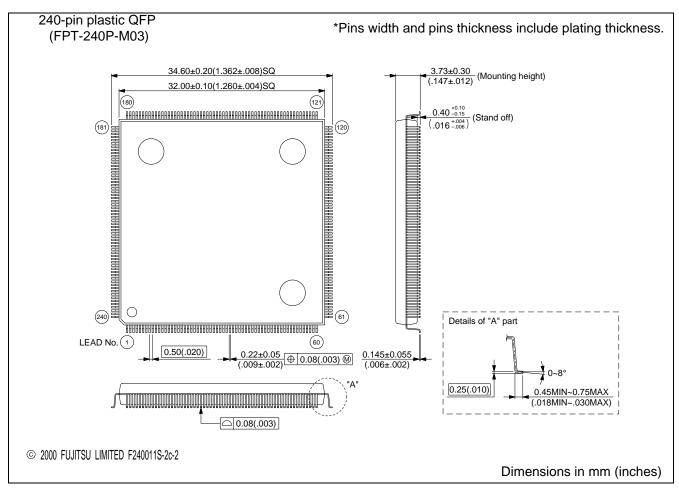
(4) PLL Standards

Doromotor	Value Unit		l lmi4	Description	
Parameter	Min	Тур	Max	Onit	Description
Input frequency (Typical)	_	14.31818	_	MHz	
Output frequency	_	_	200.45452	MHz	Multiplied by 14
Duty ratio	93.1	_	101.3	%	PLL output clock H/L pulse width ratio
Jitter	- 150	_	+ 180	ps	Cycle difference between two consecutive cycles

■ ORDERING INFORMATION

Part Number	Package	Remarks
MB86290APFVS	240-pin plastic QFP (FPT-240P-M03)	

■ PACKAGE DIMENSION



FUJITSU LIMITED

All Rights Reserved.

The contents of this document are subject to change without notice. Customers are advised to consult with FUJITSU sales representatives before ordering.

The information and circuit diagrams in this document are presented as examples of semiconductor device applications, and are not intended to be incorporated in devices for actual use. Also, FUJITSU is unable to assume responsibility for infringement of any patent rights or other rights of third parties arising from the use of this information or circuit diagrams.

The products described in this document are designed, developed and manufactured as contemplated for general use, including without limitation, ordinary industrial use, general office use, personal use, and household use, but are not designed, developed and manufactured as contemplated (1) for use accompanying fatal risks or dangers that, unless extremely high safety is secured, could have a serious effect to the public, and could lead directly to death, personal injury, severe physical damage or other loss (i.e., nuclear reaction control in nuclear facility, aircraft flight control, air traffic control, mass transport control, medical life support system, missile launch control in weapon system), or (2) for use requiring extremely high reliability (i.e., submersible repeater and artificial satellite).

Please note that Fujitsu will not be liable against you and/or any third party for any claims or damages arising in connection with above-mentioned uses of the products.

Any semiconductor devices have an inherent chance of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

If any products described in this document represent goods or technologies subject to certain restrictions on export under the Foreign Exchange and Foreign Trade Law of Japan, the prior authorization by Japanese government will be required for export of those products from Japan.

F0203

© FUJITSU LIMITED Printed in Japan